

ABSTRACT

MOLD RELEASE FILM AND METHOD FOR MANUFACTURING SEMICONDUCTOR
PACKAGE

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The present invention provides a mold release film comprising a mold release layer, an antistatic layer, and a substrate in this order. The average thickness of the mold release layer exceeds 0.1 μm . When unevenness of a surface of a face in contact with curable resin is measured by a laser microscope and a surface angle distribution of an angle (θ) formed between the normal vector of the unevenness and the normal line of a principal surface of the mold release film is obtained, the existence fraction (Φ) in a range of 10-35° is 0.12 or more. This mold release film can be used for the manufacture of a semiconductor package in which a curing-agent resin is used to seal a semiconductor device so as to form a resin sealed portion.

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